

PRODUCT RELIABILITY REPORT FOR

DS26334, Rev A3

Maxim Integrated Products

4401 South Beltwood Parkway Dallas, TX 75244-3292

Prepared by:

Don Lipps
Manager, Reliability Engineering
Maxim Integrated Products
4401 South Beltwood Pkwy.
Dallas, TX 75244-3292
Email: don.lipps@maxim-ic.com

ph: 972-371-3739

fax: 972-371-6016

Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Maxim products:

In addition, Maxim's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport/dsreliability.html.

Device Description:

A description of this device can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.

Reliability Derating:

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

```
AfT = \exp((Ea/k)^*(1/Tu - 1/Ts)) = tu/ts
```

AfT = Acceleration factor due to Temperature

tu = Time at use temperature (e.g. 55°C)

ts = Time at stress temperature (e.g. 125°C)

k = Boltzmann's Constant (8.617 x 10-5 eV/°K)

Tu = Temperature at Use (°K)

Ts = Temperature at Stress (°K)

Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

```
AfV = exp(B*(Vs - Vu))
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AfV = Acceleration factor due to Voltage

Vs = Stress Voltage (e.g. 7.0 volts)

Vu = Maximum Operating Voltage (e.g. 5.5 volts)

B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

```
Fr = X/(ts * AfV * AfT * N * 2)
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X = Chi-Sq statistical upper limit

N = Life test sample size

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

FAILURE RATE: MTTF (YRS): 73515 FITS: 1.6

DEVICE HOURS: 625640 FAILS: 0

Only data from Operating Life or similar stresses are used for this calculation.

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 B: 0 Tu: 25 °C Vu: 3.5 Volts

The reliability data follows. At the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available and may contain some generic data. "*" after DATE CODE denotes specific product data and SEQ No. to identify specific line items in the report for comments when required.

Device Information:

Process: 2P, 4M,0.35um,Sil.P1,P2Cap,Ti/TiN M1-M4,BPSG,Masked N+ESD,

Passivation: Passivation w/Nov TEOS Oxide-Nitride

Die Size: 452 x 454 Number of Transistors: 1307147

Interconnect: Aluminum / 0.5% Copper

Gate Oxide Thickness: 75 Å

ELECTRICAL CHARACTERIZATION										
DESCRIPTION	DATE CODE/SEQ		CONDITION		READPOINT		FAILS	FA#		
ESD SENSITIVITY	0632	* 1	EOS/ESD S5.1 HBM 500 VOLTS	1	PUL'S	3	0			
ESD SENSITIVITY	0632	* 2	EOS/ESD S5.1 HBM 1000 VOLTS	1	PUL'S	3	0			
ESD SENSITIVITY	0632	* 3	EOS/ESD S5.1 HBM 2000 VOLTS	1	PUL'S	3	0			
ESD SENSITIVITY	0632	* 4	EOS/ESD S5.1 HBM 4000 VOLTS	1	PUL'S	3	0			
ESD SENSITIVITY	0632	* 5	EOS/ESD S5.1 HBM 8000 VOLTS	1	PUL'S	3	0			
LATCH-UP	0632	* 6	JESD78, I-TEST 125C			6	0			
LATCH-UP	0632	* 7	JESD78, V-SUPPLY TEST 125C			6	0			
					Total:		0			

OPERATING LIFE							
DESCRIPTION	DATE CODE/SEQ	CONDITION	READ	POINT	QTY	FAILS	FA#
HIGH TEMP OP LIFE	0542	125C, 3.5 VOLTS	192	HRS	45	0	
HIGH TEMP OP LIFE	0604	125C, 3.5 VOLTS	1000	HRS	45	0	
HIGH TEMP OP LIFE	0617	125C, 3.6 VOLTS	1000	HRS	45	0	
HIGH TEMP OP LIFE	0617	125C, 3.6 VOLTS	1000	HRS	45	0	
HIGH TEMP OP LIFE	0617	125C, 3.6 VOLTS	1000	HRS	45	0	

					Total:		0
HIGH TEMP OP LIFE	0811		125C, 3.5 VOLTS	1000) HRS	45	0
HIGH TEMP OP LIFE	0716		125C, 3.5 VOLTS	1000	O HRS	45	0
HIGH TEMP OP LIFE	0650		125C, 3.5 VOLTS	1000	0 HRS	45	0
HIGH TEMP OP LIFE	0650		125C, 3.5 VOLTS	1000) HRS	45	0
HIGH TEMP OP LIFE	0641		125C, 3.5 VOLTS	1000) HRS	45	0
HIGH TEMP OP LIFE	0632		125C, 3.5 VOLTS	1000) HRS	45	0
HIGH TEMP OP LIFE	0632	* 1	125C, 3.5 VOLTS	1000) HRS	45	0
HIGH TEMP OP LIFE	0620		125C, 3.5 VOLTS	1000) HRS	45	0
HIGH TEMP OP LIFE	0618		125C, 3.5 VOLTS	1000) HRS	77	0

FAILURE RATE: MTTF (YRS): 73515 FITS: 1.6

DEVICE HOURS: 625640 FAILS: 0